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=> s spin etching
      214967 SPIN
      56925 ETCHING
L1      10 SPIN ETCHING
          (SPIN(W)ETCHING)
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"N" 22 13 1-10

L1 ANSWER 1 OF 10 INSPEC (C) 2004 IEE on STN

Full Text References

AN 2004:8024784 INSPEC DN B2004-08-2240-008
TI The challenge of ultra thin chip assembly.
AU Feil, M.; Adler, C.; Hemmetzberger, D.; Konig, M.; Bock, K.
(Fraunhofer-Inst. for Reliability & Microintegration, Munchen, Germany)
SO 2004 Proceedings. 54th Electronic Components and Technology Conference
(IEEE Cat. No.04CH37546)
Piscataway, NJ, USA: IEEE, 2004. p.35-40 Vol.1 of 2090 pp. 7 refs.
Conference: Las Vegas, NV, USA, 1-4 June 2004
Price: CCCC 0-7803-8365-6/04/\$20.00
ISBN: 0-7803-8365-6
DT Conference Article
TC Practical
CY United States
LA English

L1 ANSWER 2 OF 10 INSPEC (C) 2004 IEE on STN

Full Text References

AN 2004:7955919 INSPEC DN B2004-06-2550E-056
TI Fabrication of thin film transistors on plastic substrates by spin
etching and device transfer process.
AU Shuo-Cheng Wang; Chung-Ti Hsu; Ching-Fa Yeh; Jen-Chung Lou (Dept. of
Electron. Eng. & Inst. of Electron., Nat. Chiao Tung Univ., Hsinchu,
Taiwan)
SO Proceedings of the SPIE - The International Society for Optical
Engineering (2004) vol.5276, no.1, p.376-83. 11 refs.
Published by: SPIE-Int. Soc. Opt. Eng
Price: CCCC 0277-786X/04/\$15.00
CODEN: PSISDG ISSN: 0277-786X
SICI: 0277-786X(2004)5276:1L.376:FTFT;1-4
Conference: Device and Process Technologies for MEMS, Microelectronics,
and Photonics III. Perth, SA, Australia, 10-12 Dec 2003
DT Conference Article; Journal
TC Application; Experimental
CY United States
LA English

L1 ANSWER 3 OF 10 INSPEC (C) 2004 IEE on STN

Full Text References

AN 2003:7654817 INSPEC DN B2003-07-2550E-051
TI Stability investigation of single-wafer process by using a spin etcher.
AU Tsung-Kuei Kang (Dept. of Electron. Eng., Feng-Chia Univ., Taichung,
Taiwan); Chih-Cheng Wang; Bing-Yue Tsui; Wen-Luh Yang; Feng-Tso Chien;
Shui-Yuan Yang; Chin-Yen Chang; Yuan-Hsin Li
SO Electrochemical and Solid-State Letters (July 2003) vol.6, no.7, p.G85-7.
10 refs.
Published by: Electrochem. Soc
Price: CCCC 1099-0062/2003/6(7)/G85/3/\$7.00
CODEN: ESLEF6 ISSN: 1099-0062
SICI: 1099-0062(200307)6:7L.g85:SISW;1-T
DT Journal
TC Application; Experimental
CY United States
LA English

L1 ANSWER 4 OF 10 INSPEC (C) 2004 IEE on STN

Full Text References

AN 2003:7636124 INSPEC DN B2003-06-0170J-037
TI Packaging technologies for flexible systems.
AU Kallmayer, C.; Bock, K.; Aschenbrenner, R.; Reichl, H. (Fraunhofer Inst.
Zuverlässigkeit und Mikrointegration, Berlin, Germany)
SO Proceedings International Conference and Exhibition on Advanced Packaging
and Systems. ICAPS (SPIE Vol.4828)

Washington, DC, USA: IMAPS - Int. Microelectronics & Packaging Soc, 2002.

p.43-5 of 274 pp. 4 refs.

Conference: Reno, NV, USA, 10-13 March 2002

Sponsor(s): IMAPS

ISBN: 0-930815-65-3

DT Conference Article

TC General Review; Practical

CY United States

LA English

L1 ANSWER 5 OF 10 INSPEC (C) 2004 IEE on STN

Full Text Record

AN 2002:7434575 INSPEC DN B2002-12-2550E-043

TI Preparation of silicon-on-insulator wafer using spin etching and a subsequent selective etching process.

AU Seong-Eun Lee; Seung-Jin Oh; Sang-Mun So; Heon-Do Kim; Sung-Woong Chung; Hyun-Chul Sohn (Memory R&D Div., Hynix Semicond. Co. Ltd., Kyoungki, South Korea)

SO Japanese Journal of Applied Physics, Part 1 (Regular Papers, Short Notes & Review Papers) (Aug. 2002) vol.41, no.8, p.5024-9. 24 refs.

Published by: Japan Soc. Appl. Phys

CODEN: JAPNDE ISSN: 0021-4922

SICI: 0021-4922(200208)41:8L.5024:PSIW;1-S

DT Journal

TC Practical; Experimental

CY Japan

LA English

L1 ANSWER 6 OF 10 INSPEC (C) 2004 IEE on STN

Full Text Record

AN 2001:7039608 INSPEC DN B2001-10-7230M-028

TI A CMOS integrated three-axis accelerometer fabricated with commercial submicrometer CMOS technology and bulk-micromachining.

AU Takao, H. (Dept. of Electr. & Electron. Eng., Toyohashi Univ. of Technol., Japan); Fukumoto, H.; Ishida, M.

SO IEEE Transactions on Electron Devices (Sept. 2001) vol.48, no.9, p.1961-8. 18 refs.

Doc. No.: S0018-9383(01)06903-9

Published by: IEEE

Price: CCCC 0018-9383/2001/\$10.00

CODEN: IETDAI ISSN: 0018-9383

SICI: 0018-9383(200109)48:9L.1961:CITA;1-0

DT Journal

TC Experimental

CY United States

LA English

L1 ANSWER 7 OF 10 INSPEC (C) 2004 IEE on STN

Full Text Record

AN 2001:6799432 INSPEC DN B2001-02-2570-002

TI Ultra thin ICs open new dimensions for microelectronic systems.

AU Klink, G.; Landesberger, C.; Feil, M.; Ansorge, F.; Aschenbrenner, R. (Fraunhofer Inst. for Reliability & Microintegration IZM, Munich, Germany)

SO Advancing Microelectronics (July-Aug. 2000) vol.27, no.4, p.23-5. 7 refs.

Published by: IMAPS-Int. Microelectron. & Packaging Soc

CODEN: ADMIFA

DT Journal

TC Application; Practical

CY United States

LA English

L1 ANSWER 8 OF 10 INSPEC (C) 2004 IEE on STN

Full Text Record

AN 2000:6636119 INSPEC DN B2000-08-7230M-047
TI Fabrication of a three-axis accelerometer integrated with commercial 0.8
mu m-CMOS circuits.
AU Takao, H. (Dept. of Electr. & Electron. Eng., Toyohashi Univ. of Technol.,
Japan); Fukumoto, H.; Ishida, M.
SO Proceedings IEEE Thirteenth Annual International Conference on Micro
Electro Mechanical Systems (Cat. No.00CH36308)
Piscataway, NJ, USA: IEEE, 2000. p.781-6 of xiv+810 pp. 6 refs.
Conference: Miyazaki, Japan, 23-27 Jan 2000
Sponsor(s): IEEE Robotics & Autom. Soc.; Micromachine Center
Price: CCCC 0 7803 5273 4/2000/\$10.00
ISBN: 0-7803-5273-4
DT Conference Article
TC Practical; Experimental
CY United States
LA English

L1 ANSWER 9 OF 10 INSPEC (C) 2004 IEE on STN

 
Full Text

AN 1991:3955183 INSPEC DN B91056059
TI Spin etcher for removal of backside depositions.
AU Gaulhofer, E. (AMS Microsystems, Graz, Austria)
SO Solid State Technology (May 1991) vol.34, no.5, p.57-8, 219. 0 refs.
CODEN: SSTEAP ISSN: 0038-111X
DT Journal
TC Practical
CY United States
LA English

L1 ANSWER 10 OF 10 INSPEC (C) 2004 IEE on STN

 
Full Text

AN 1989:3457364 INSPEC DN A89117018; B89061493
TI Silicon surface passivation by hydrogen termination: a comparative study
of preparation methods.
AU Fenner, D.B. (Xerox Palo Alto Res. Center, CA, USA); Biegelsen, D.K.;
Bringans, R.D.
SO Journal of Applied Physics (1 July 1989) vol.66, no.1, p.419-24. 23 refs.
Price: CCCC 0021-8979/89/130419-06\$02.40
CODEN: JAPIAU ISSN: 0021-8979
DT Journal
TC Experimental
CY United States
LA English

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